FIG. 1

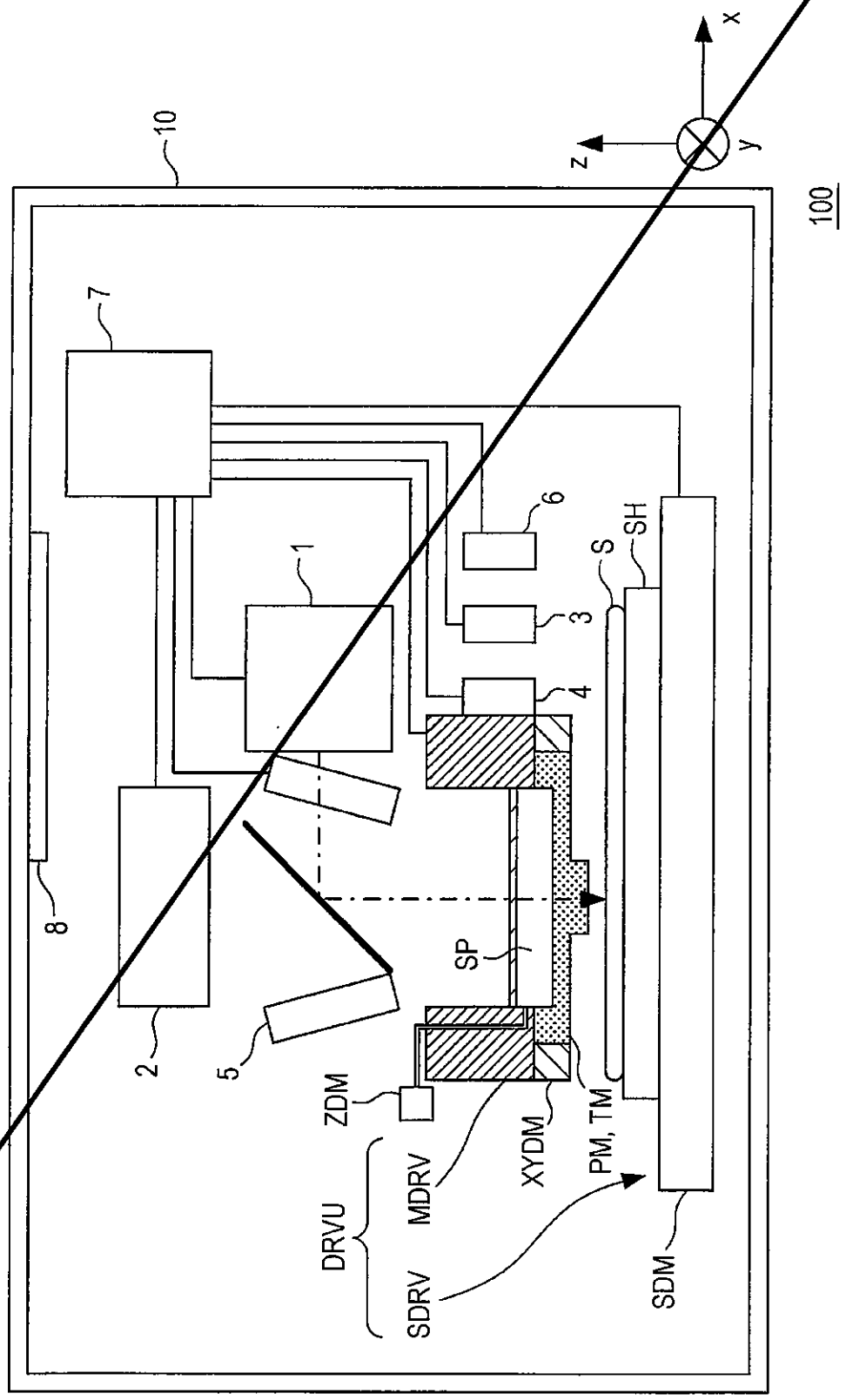


FIG. 2

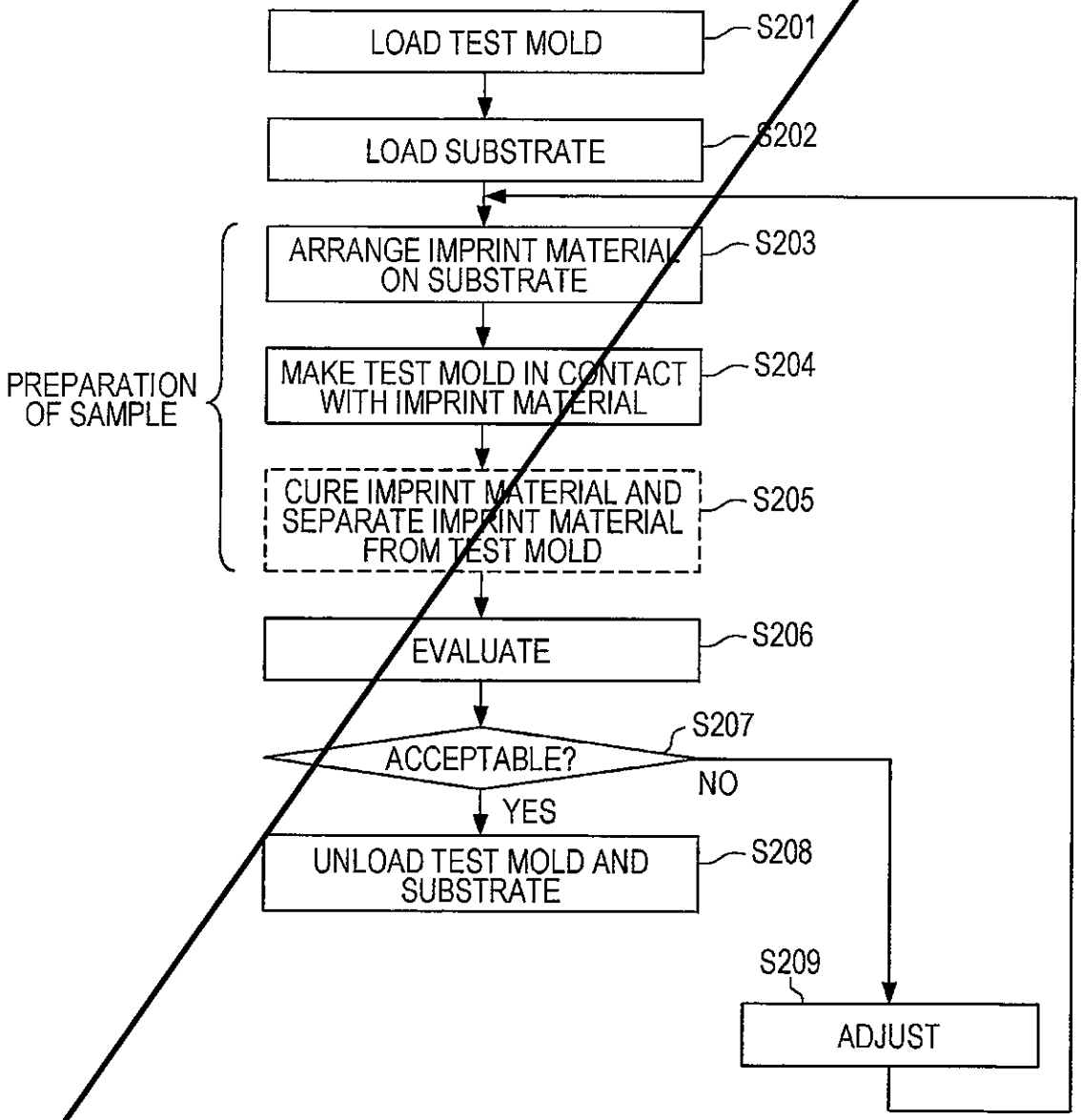

LOAD TEST MOLD
S201
LOAD SUBSTRATE
S202
ARRANGE IMPRINT MATERIAL ON SUBSTRATE
S203
MAKE TEST MOLD IN CONTACT WITH IMPRINT MATERIAL
S204
CURE IMPRINT MATERIAL AND SEPARATE IMPRINT MATERIAL FROM TEST MOLD
S205
PREPARATION OF SAMPLE
EVALUATE
S206
ACCEPTABLE?
S207
NO
YES
UNLOAD TEST MOLD AND SUBSTRATE
S208
S209
ADJUST

FIG. 3A



FIG. 3B



FIG. 4A

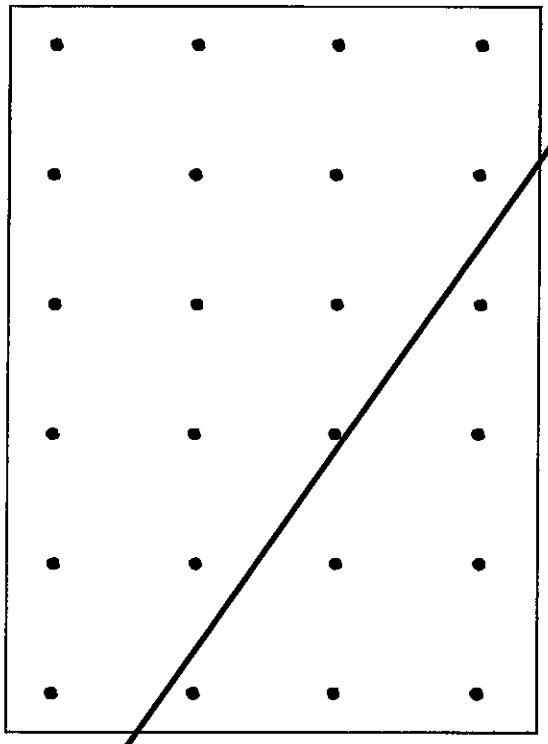


FIG. 4B

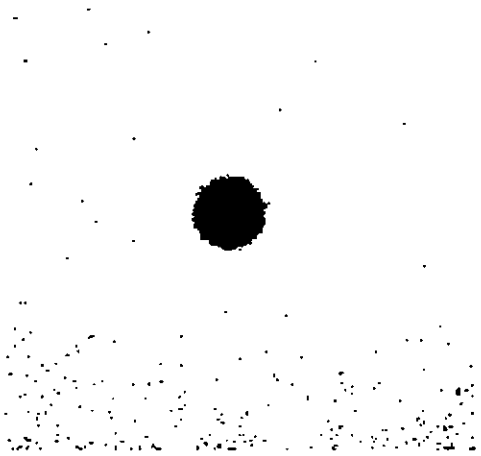


FIG. 5A

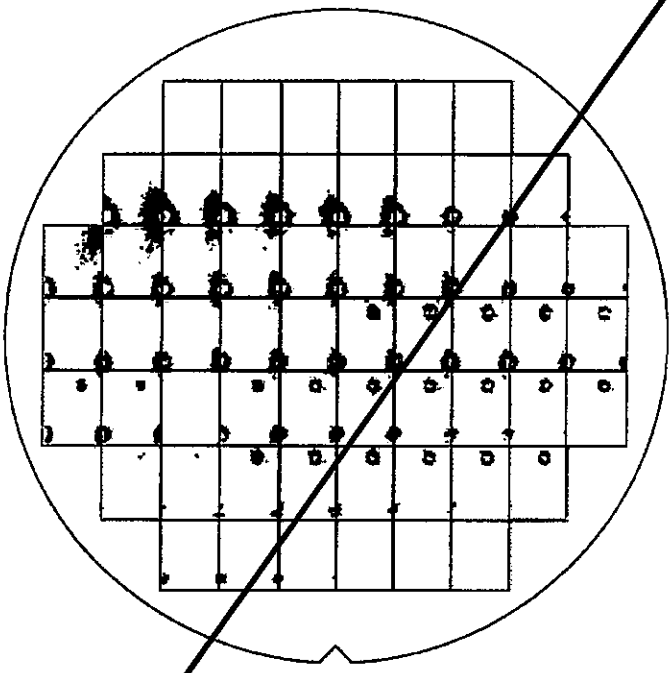


FIG. 5B

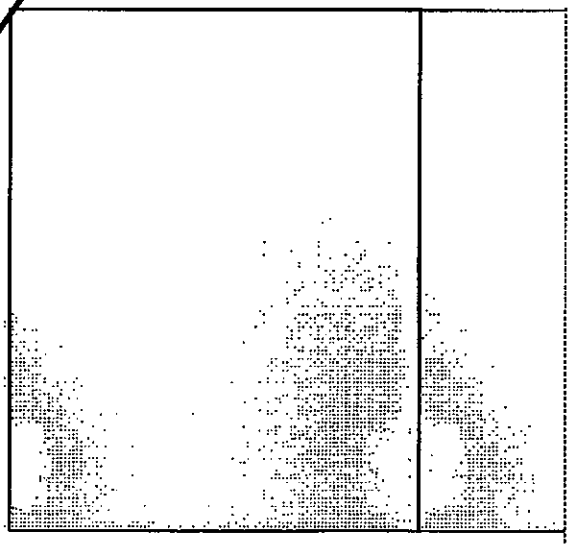


FIG. 6A

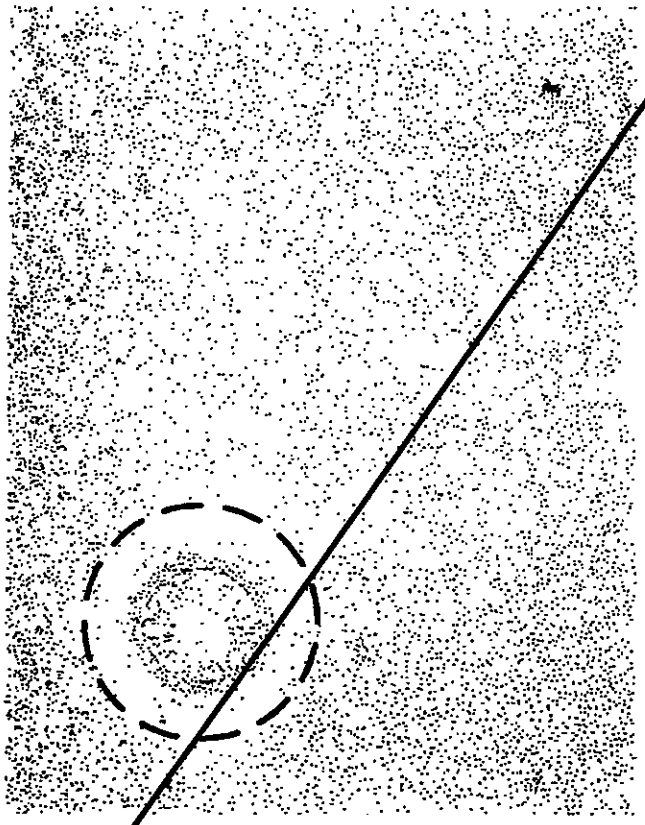


FIG. 6B

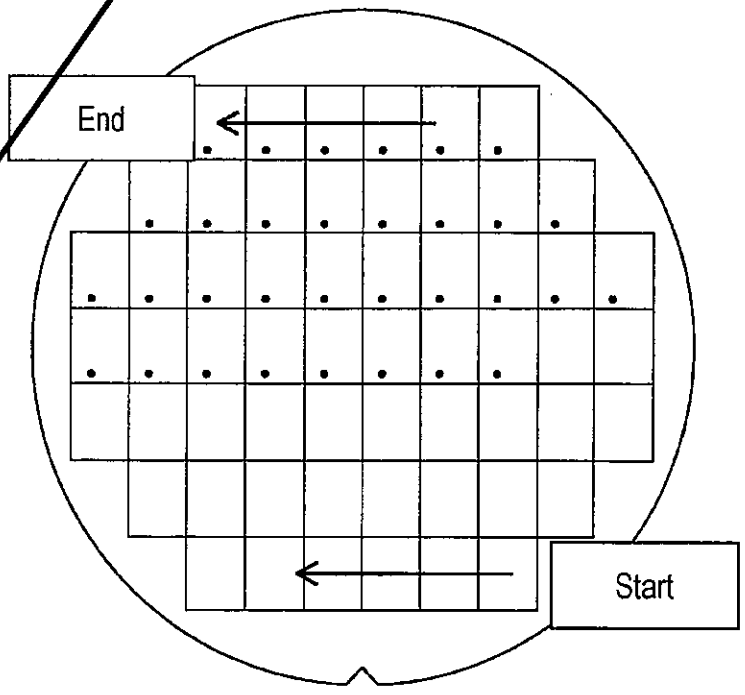


FIG. 7

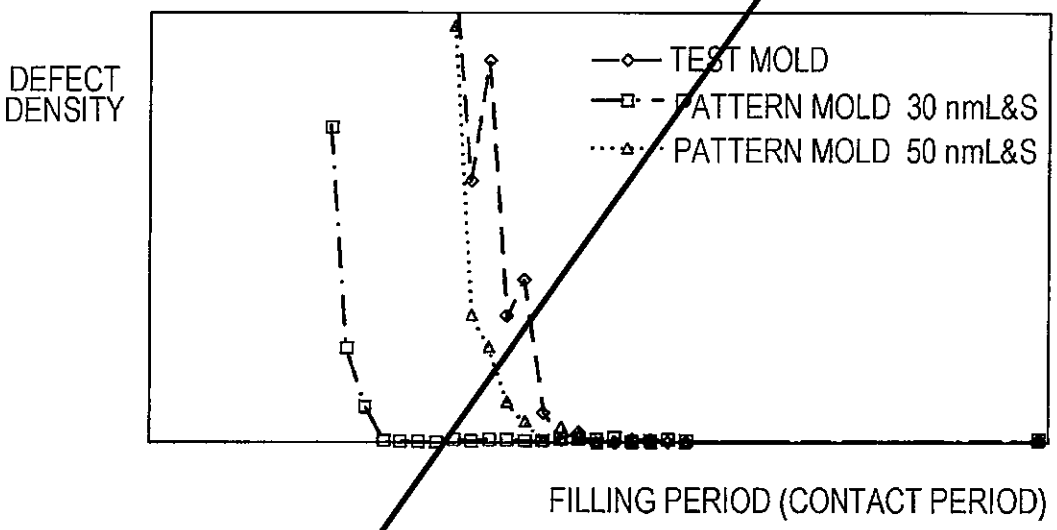

DEFECT DENSITY
TEST MOLD
PATTERN MOLD 30 nmL&S
PATTERN MOLD 50 nmL&S
FILLING PERIOD (CONTACT PERIOD)

FIG. 8

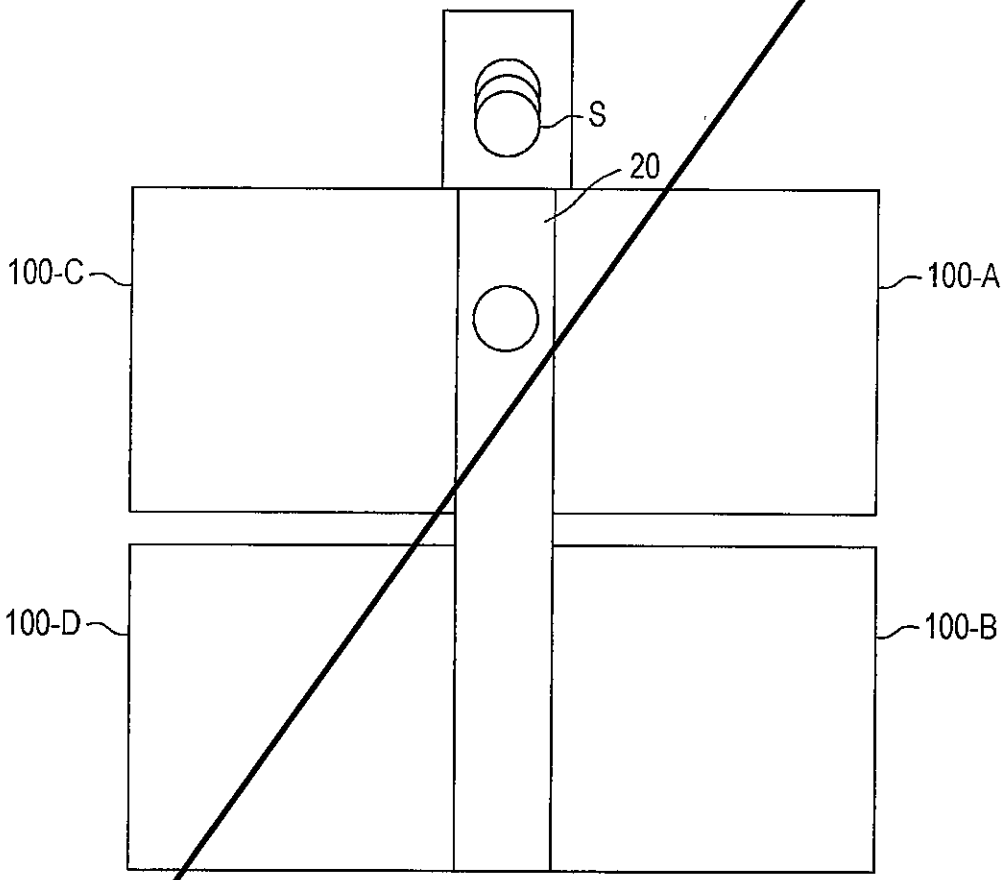


FIG. 9

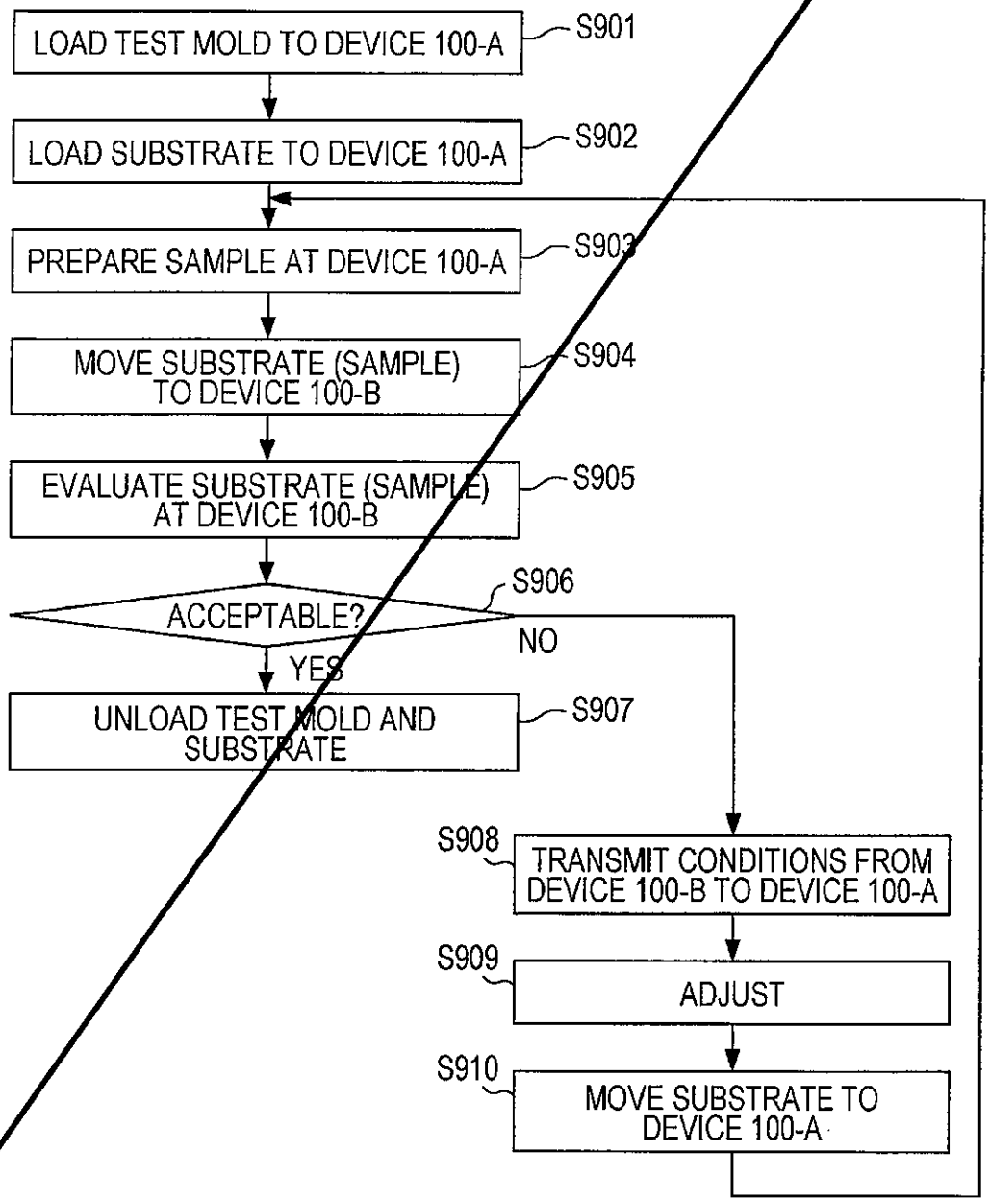

LOAD TEST MOLD TO DEVICE 100-A
S901
LOAD SUBSTRATE TO DEVICE 100-A
S902
PREPARE SAMPLE AT DEVICE 100-A
S903
MOVE SUBSTRATE (SAMPLE) TO DEVICE 100-B
S904
EVALUATE SUBSTRATE (SAMPLE) AT DEVICE 100-B
S905
ACCEPTABLE?
S906
NO
YES
UNLOAD TEST MOLD AND SUBSTRATE
S907
S908
TRANSMIT CONDITIONS FROM DEVICE 100-B TO DEVICE 100-A
S909
ADJUST
S910
MOVE SUBSTRATE TO DEVICE 100-A

FIG. 1

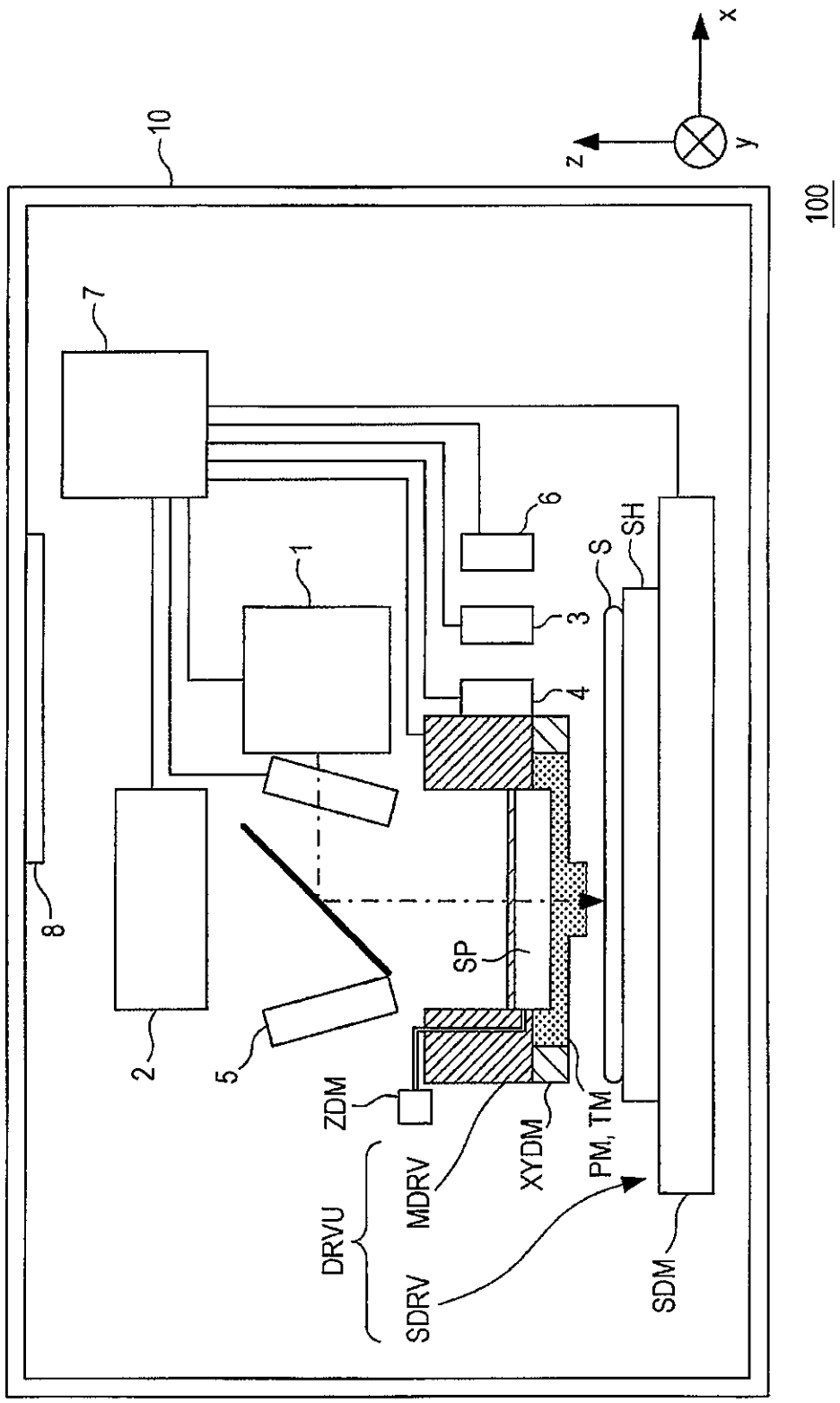


FIG. 2

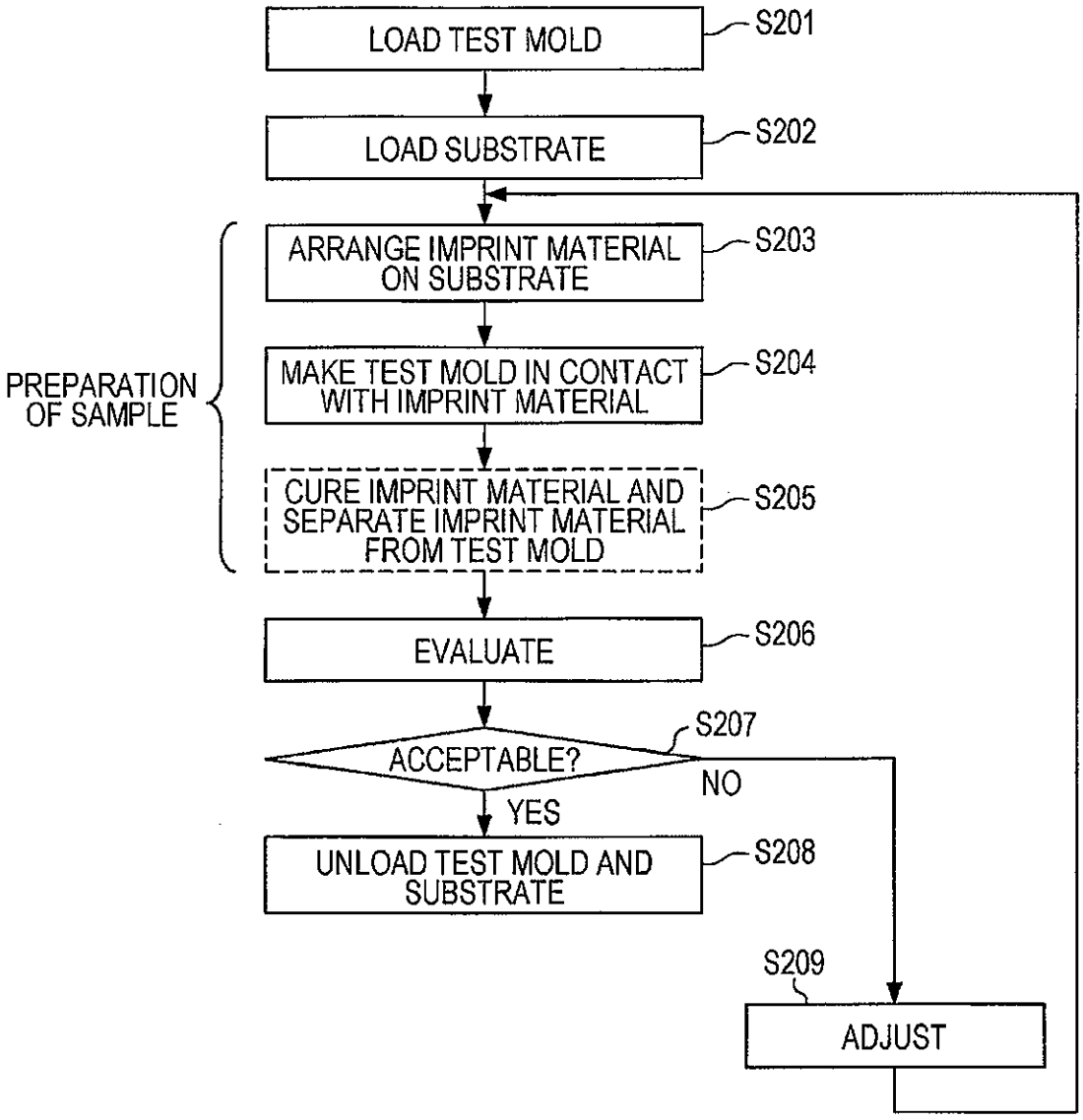

LOAD TEST MOLD
S201
LOAD SUBSTRATE
S202
ARRANGE IMPRINT MATERIAL ON SUBSTRATE
S203
MAKE TEST MOLD IN CONTACT WITH IMPRINT MATERIAL
S204
CURE IMPRINT MATERIAL AND SEPARATE IMPRINT MATERIAL FROM TEST MOLD
S205
PREPARATION OF SAMPLE
EVALUATE
S206
ACCEPTABLE?
S207
NO
YES
UNLOAD TEST MOLD AND SUBSTRATE
S208
S209
ADJUST

FIG. 3A



FIG. 3B



FIG. 4A

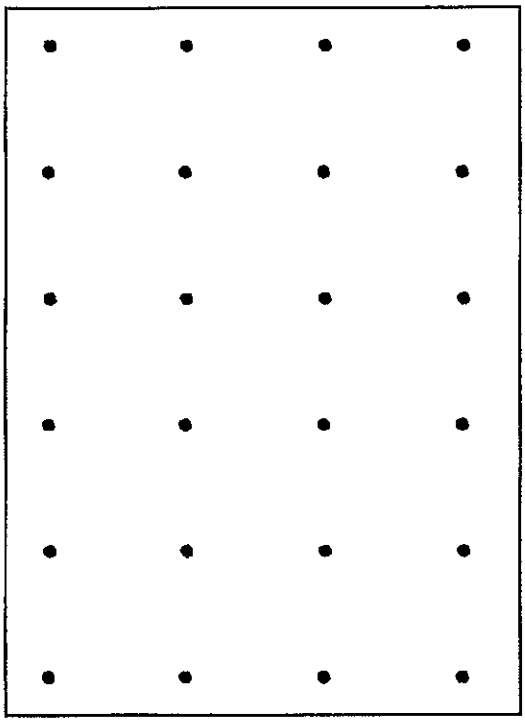


FIG. 4B



FIG. 5A

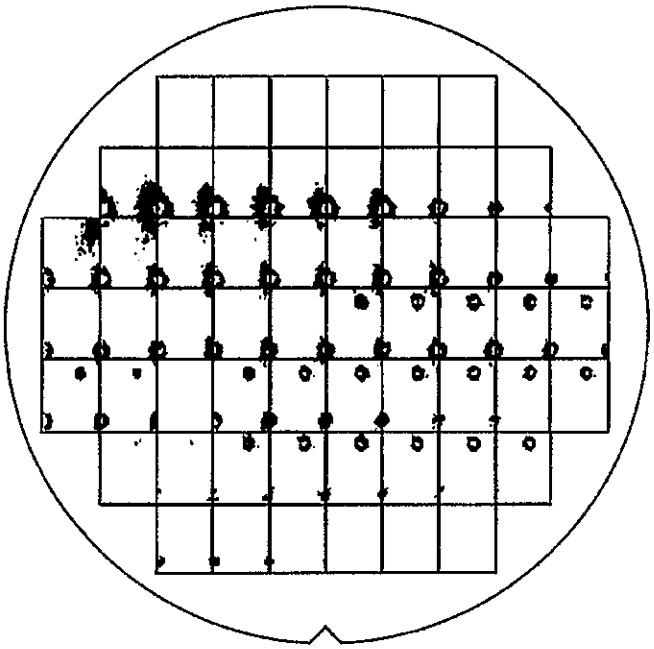


FIG. 5B

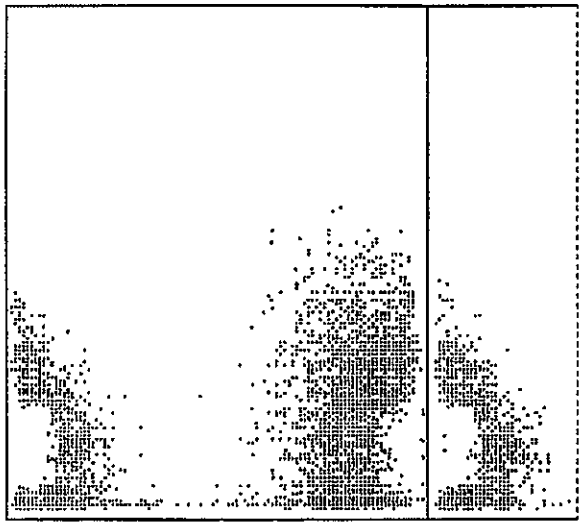


FIG. 6A

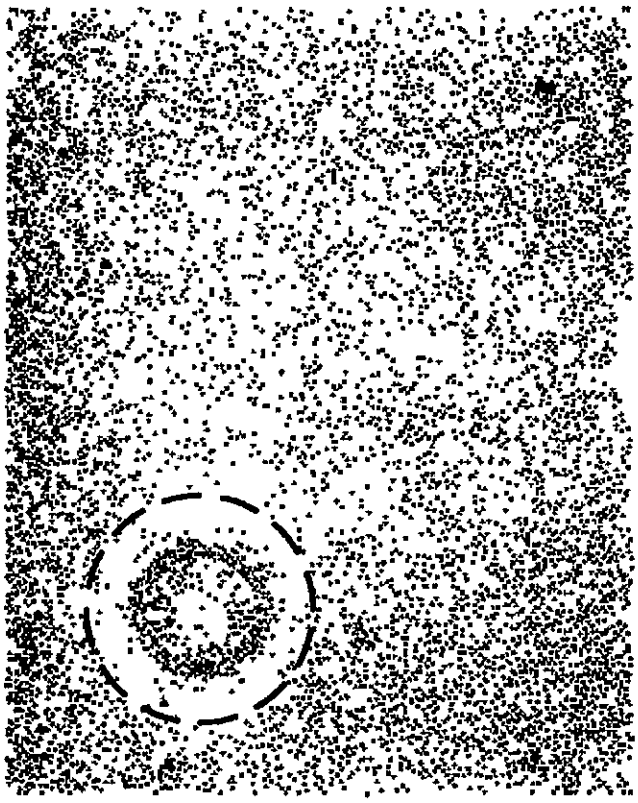


FIG. 6B

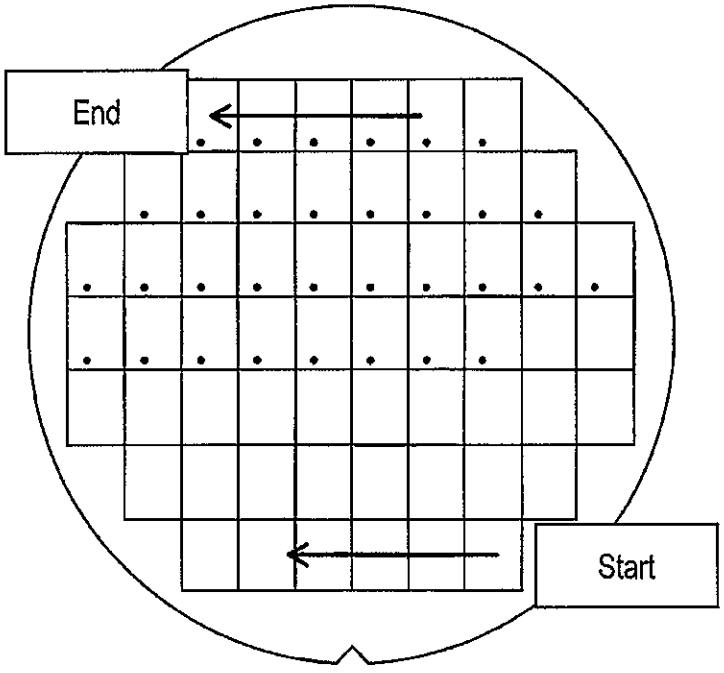


FIG. 7

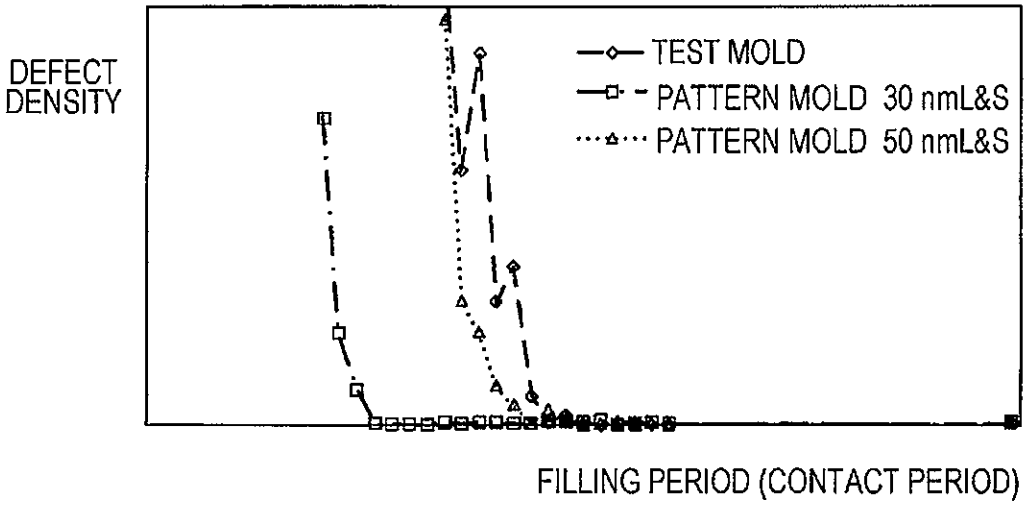

DEFECT
DENSITY
TEST MOLD
PATTERN MOLD 30 nmL&S
PATTERN MOLD 50 nmL&S
FILLING PERIOD (CONTACT PERIOD)

FIG. 8

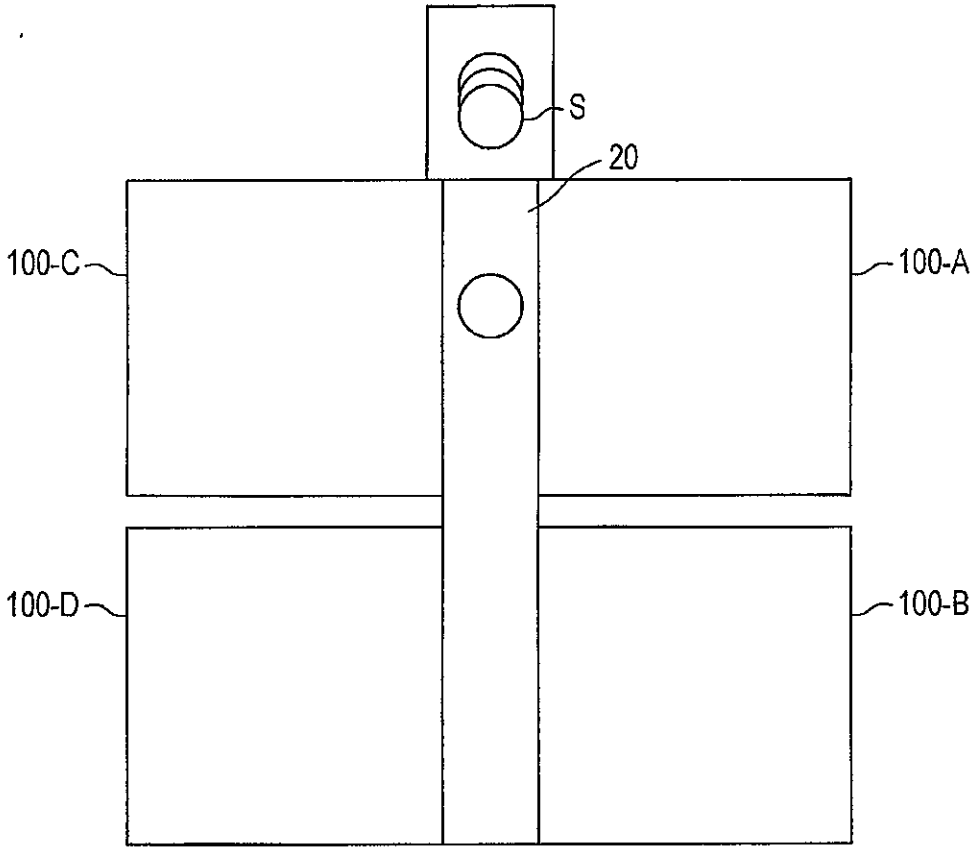
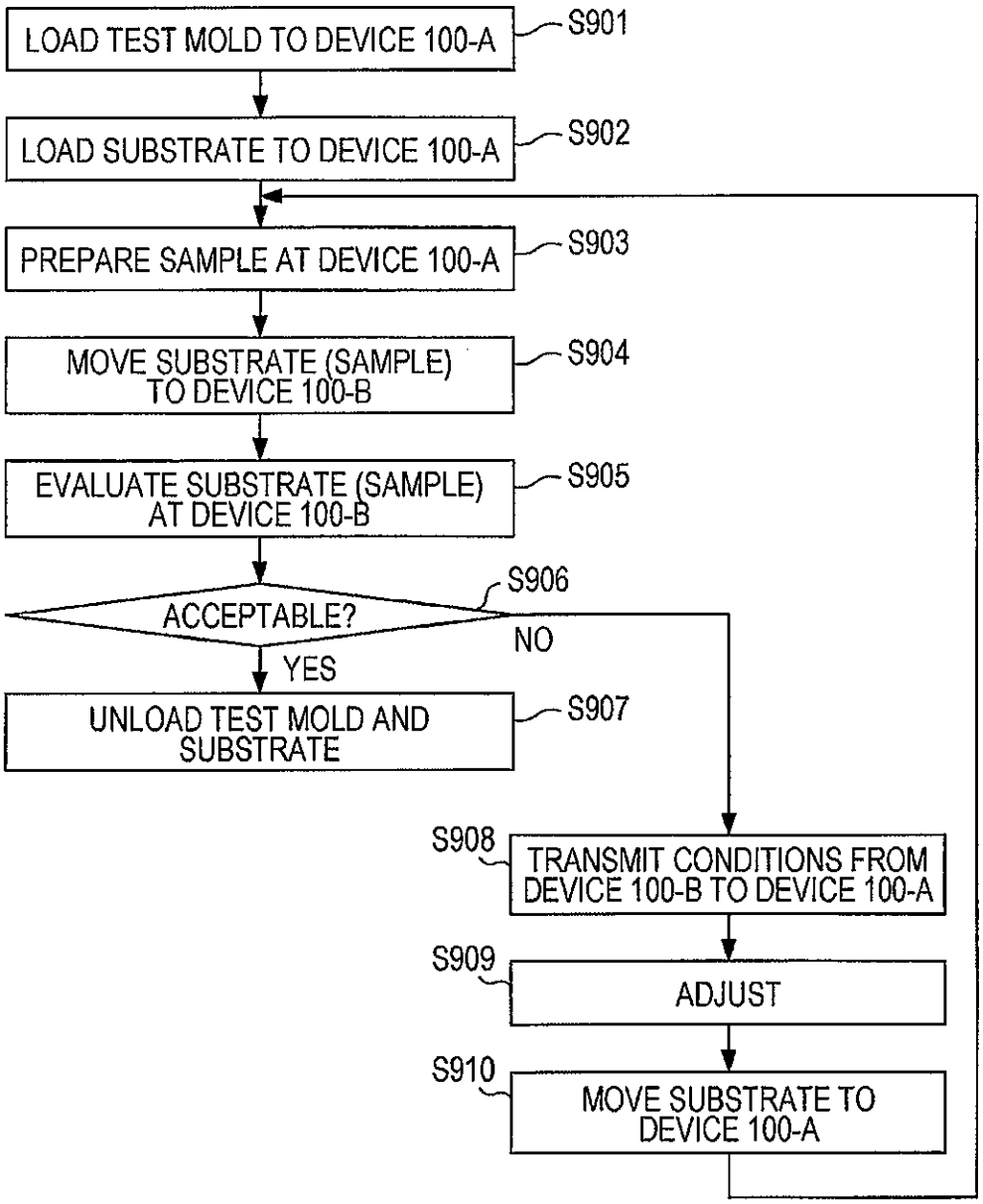


FIG. 9


LOAD TEST MOLD TO DEVICE 100-A
S901
LOAD SUBSTRATE TO DEVICE 100-A
S902
PREPARE SAMPLE AT DEVICE 100-A
S903
MOVE SUBSTRATE (SAMPLE) TO DEVICE 100-B
S904
EVALUATE SUBSTRATE (SAMPLE) AT DEVICE 100-B
S905
ACCEPTABLE?
S906
NO
YES
UNLOAD TEST MOLD AND SUBSTRATE
S907
S908
TRANSMIT CONDITIONS FROM DEVICE 100-B TO DEVICE 100-A
S909
ADJUST
S910
MOVE SUBSTRATE TO DEVICE 100-A